



SOT1443-7

wafer level chip-scale package; 30 bumps; 0.4 mm pitch, 2.44 mm x 2.2 mm x 0.525 mm body (backside coating included)

13 May 2019

Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP
Package type industry code	WLCSP30
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	16-04-2019
Manufacturer package code	98ASA01432D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	2.44	-	mm
package width	-	2.2	-	mm
package height	-	0.525	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	30	-	



wafer level chip-scale package; 30 bumps; 0.4 mm pitch, 2.44 mm x 2.2 mm x 0.525 mm body (backside coating included)

2 Package outline

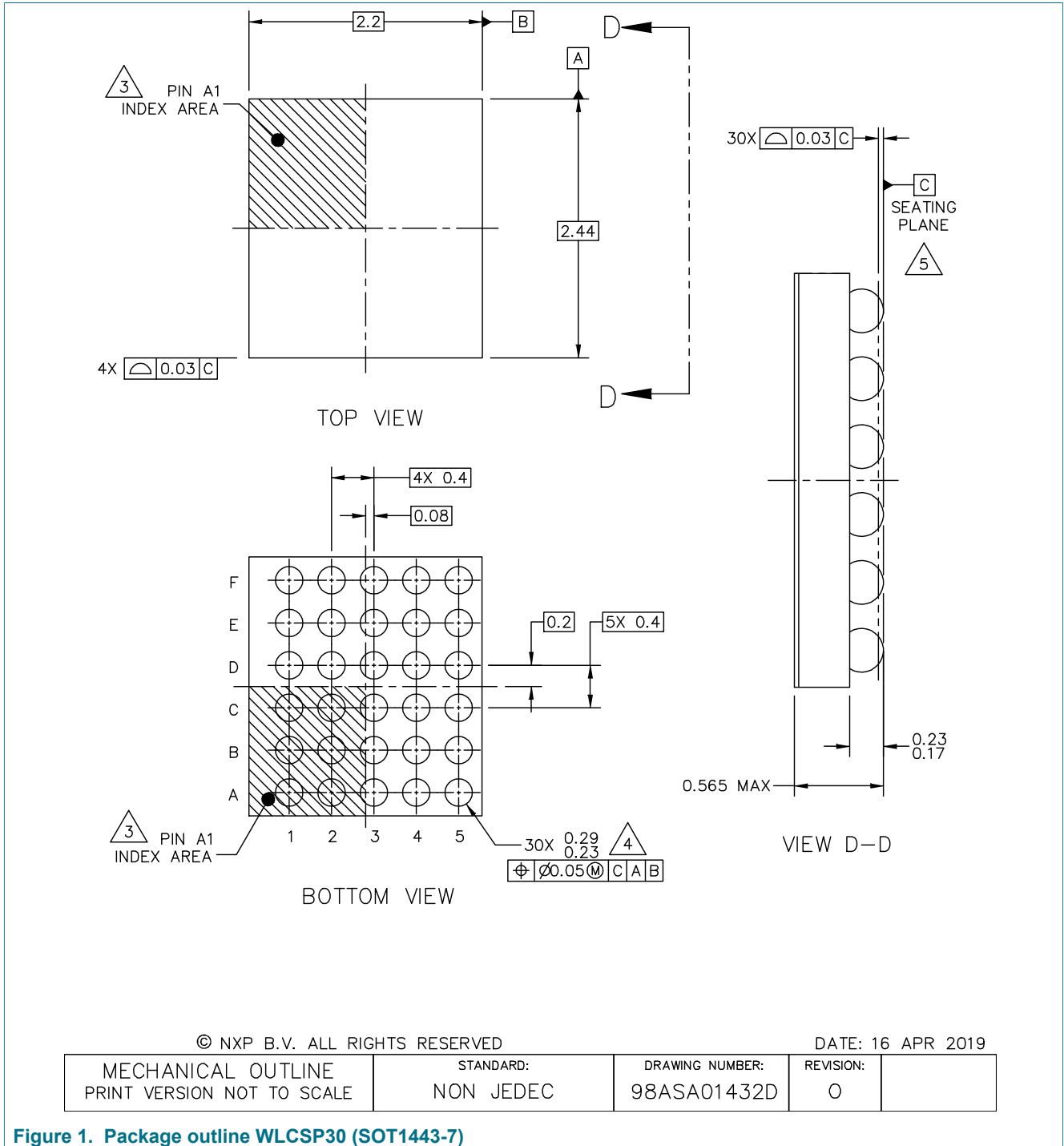
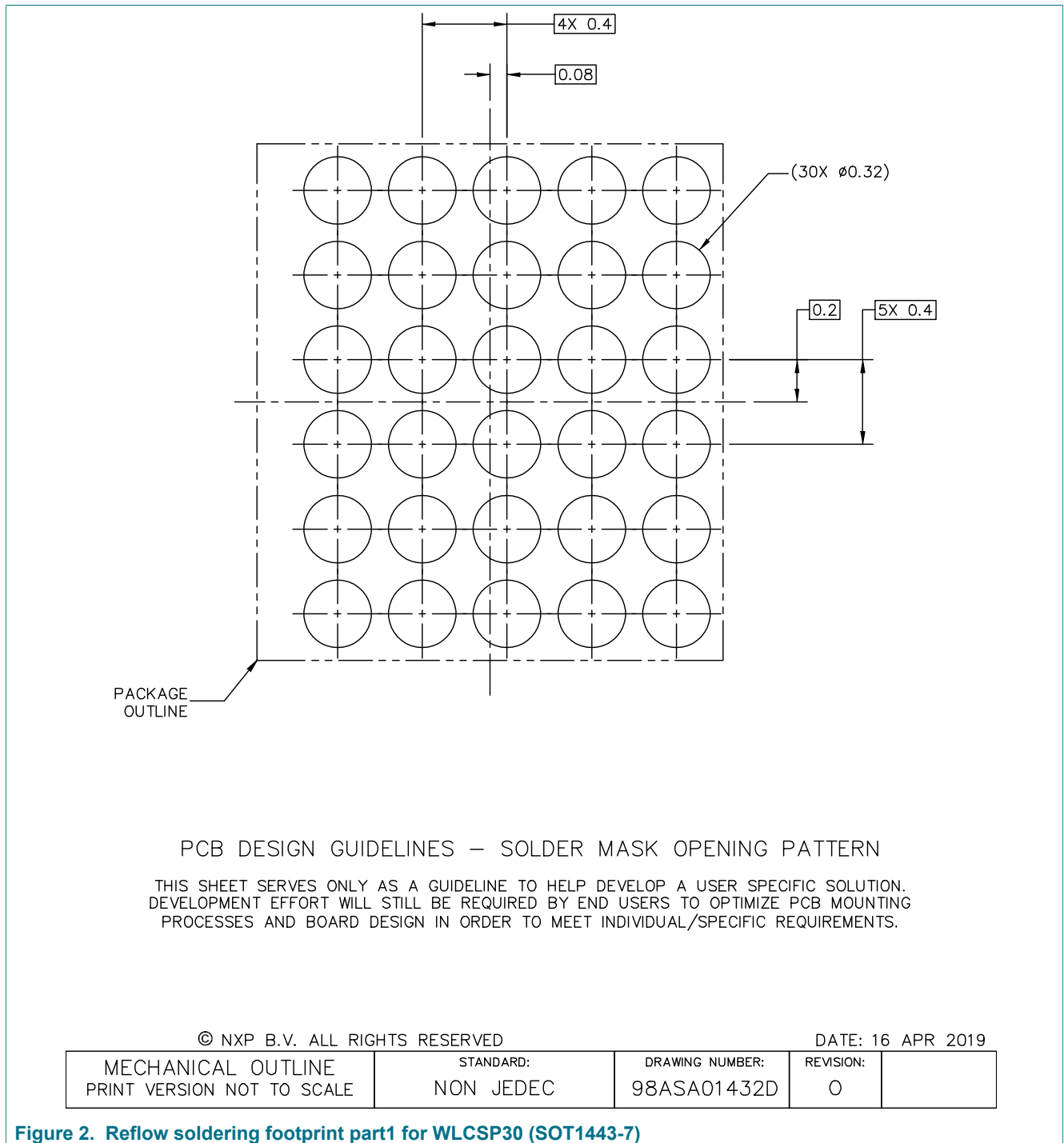


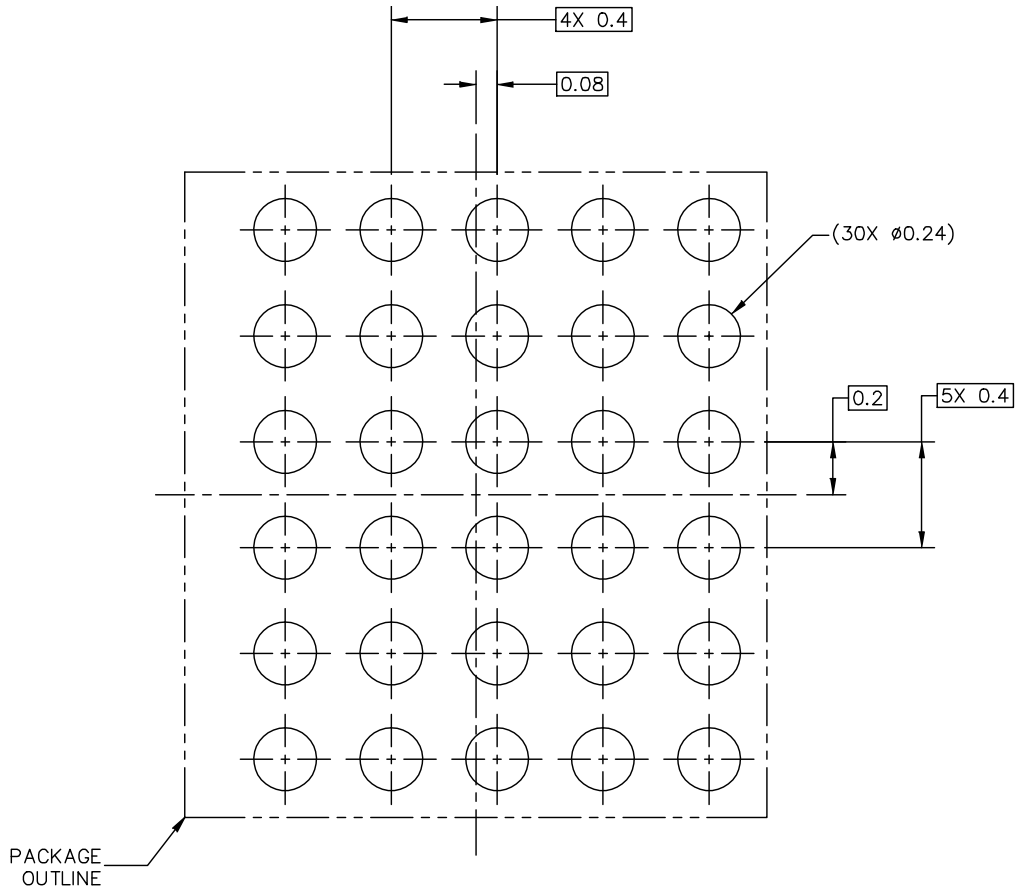
Figure 1. Package outline WLCSP30 (SOT1443-7)

wafer level chip-scale package; 30 bumps; 0.4 mm pitch, 2.44 mm x 2.2 mm x 0.525 mm body (backside coating included)

3 Soldering



wafer level chip-scale package; 30 bumps; 0.4 mm pitch, 2.44 mm x 2.2 mm body (backside coating included)



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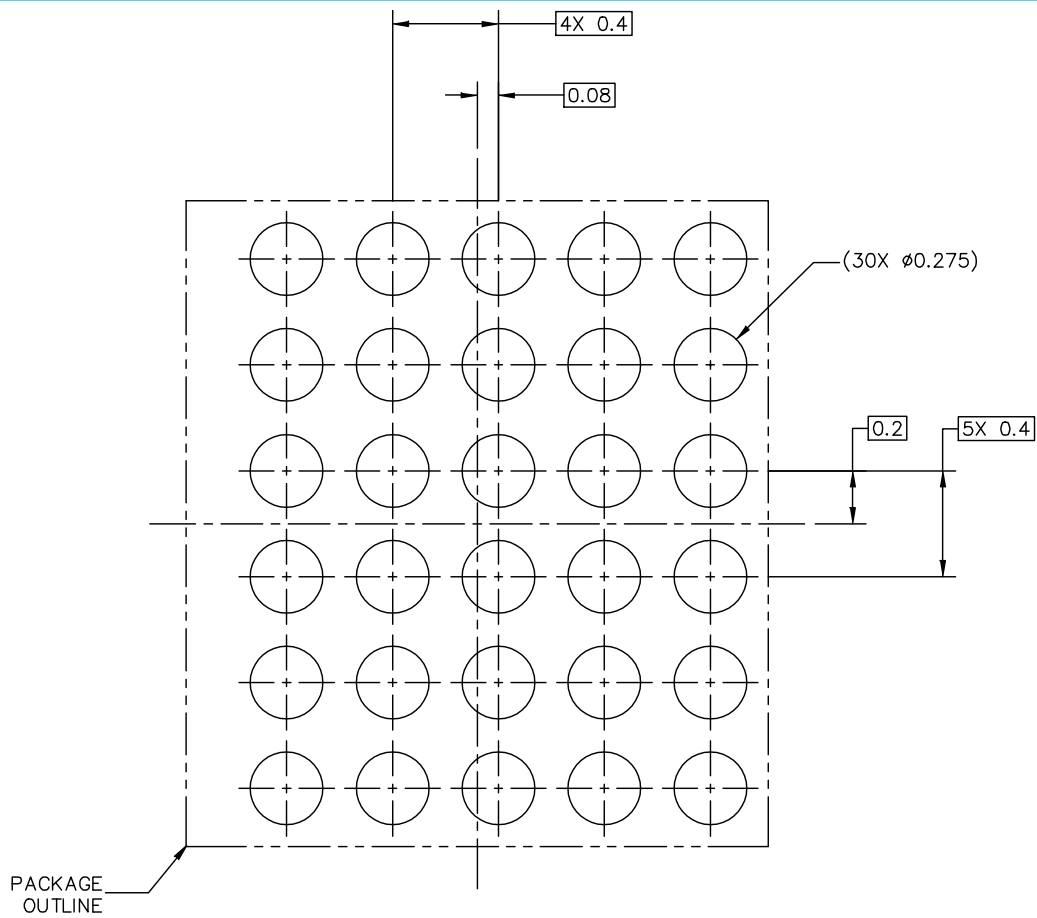
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DATE: 16 APR 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01432D	REVISION: 0	
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Figure 3. Reflow soldering footprint part2 for WLCSP30 (SOT1443-7)

wafer level chip-scale package; 30 bumps; 0.4 mm pitch, 2.44 mm x 2.2 mm x 0.525 mm body (backside coating included)



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for WLCSP30 (SOT1443-7)

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NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

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Figure 5. Package outline note WLCSP30 (SOT1443-7)

4 Legal information

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